

## Title (en)

Connector assembly for printed circuit boards.

## Title (de)

Verbinderanordnung für gedruckte Leiterplatten.

## Title (fr)

Ensemble de connexion pour cartes de circuits imprimés.

## Publication

**EP 0446980 A1 19910918 (EN)**

## Application

**EP 91200396 A 19910225**

## Priority

NL 9000578 A 19900314

## Abstract (en)

A connector assembly for printed circuit boards, comprises a first connector element with a first housing of insulating material and regularly arranged male signal and ground contacts connectable to a printed circuit board, and a second connector element with a second housing of insulating material, which can be inserted with a mating side into the first housing, and with regularly arranged female signal and ground contacts with a connection element. These female contacts will contact the corresponding male contacts when the second housing is received in the first housing. The second connector element is provided with a plurality of outer conductors, each of said outer conductors mainly enclosing at least one signal contact in a circumferential direction and each of said outer conductors being adapted to contact the adjacent ground contacts of the/each corresponding signal contact of the first connector element. <IMAGE>

## IPC 1-7

**H01R 23/68**

## IPC 8 full level

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## Citation (search report)

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## Designated contracting state (EPC)

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